Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

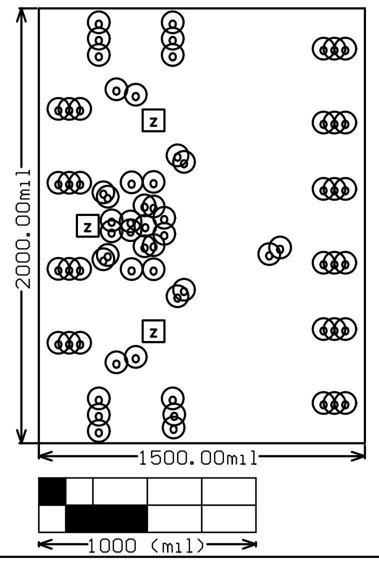
Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER ______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ______
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

DRILL CHART: TOP to L2_GND			
ALL UNITS ARE IN INCHES			
FIGURE	SIZE	PLATED	QTY
◎	0.01	PLATED	4

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN INCHES			
FIGURE	SIZE	PLATED	QTY
◎	0.01	PLATED	67
z	0.055	PLATED	3



TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = [illegible]
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

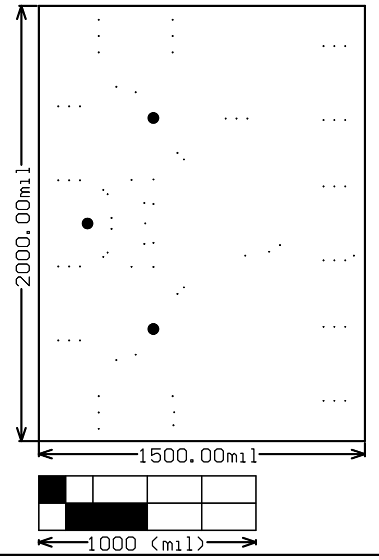
DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ________
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER________
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ________
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ________
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ________
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ________
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = M20 Board Dimensions
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

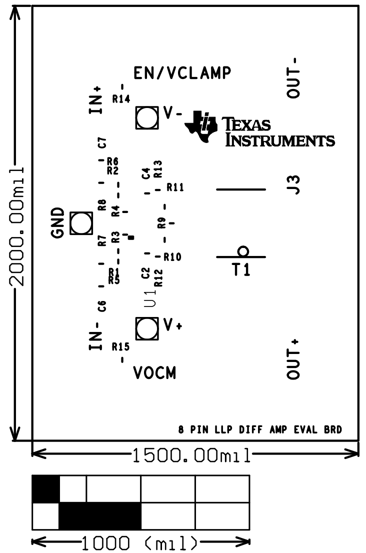
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ______
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600016	REV: A	
LAYER NAME = [illegible]			
PLOT NAME = LMH6552SDEVAL.GM11	GENERATED : 8/14/2013 4:52:55 PM		TEXAS INSTRUMENTS

TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

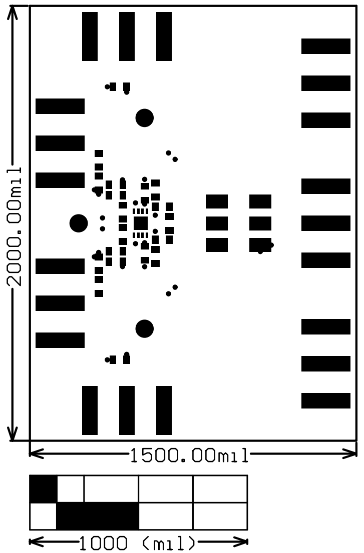
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ______
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = M1[illegible]ons
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

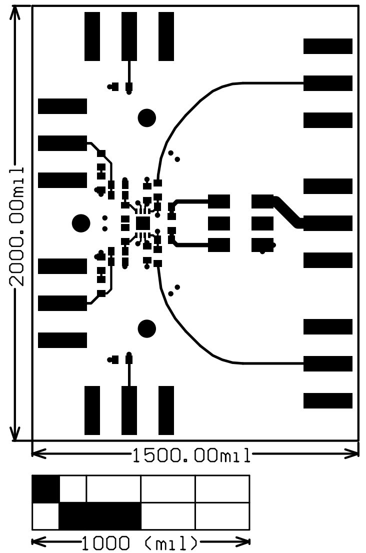
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ____________
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER____________
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ____________
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ____________
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ________
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ____________
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ____________
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ____________
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

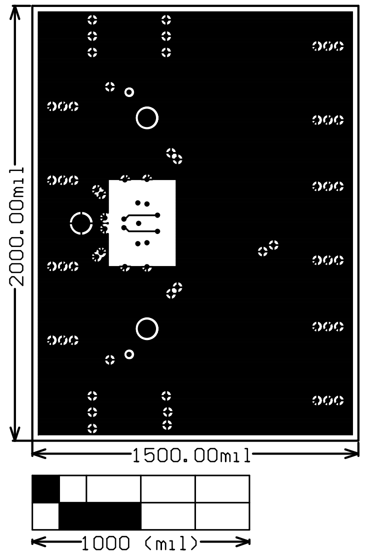
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV600016	REV: A		
LAYER NAME = M1 Board Dimensions				
PLOT NAME = LMH6552SDEVAL.GM11	GENERATED : 8/14/2013 4:52:55 PM			TEXAS INSTRUMENTS

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009



Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ________
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER________
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ________
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ________
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ________
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ________
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = M20BoardkDuelmsaons
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______

COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______

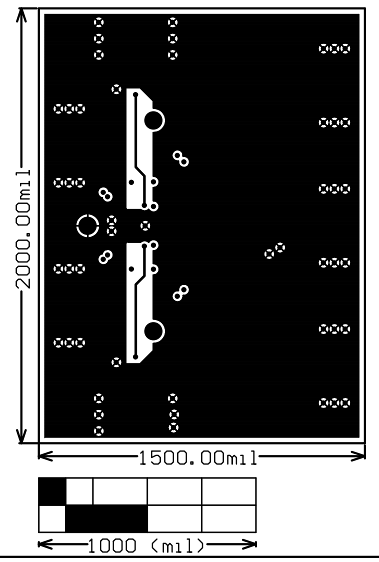
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ______

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = [illegible]
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

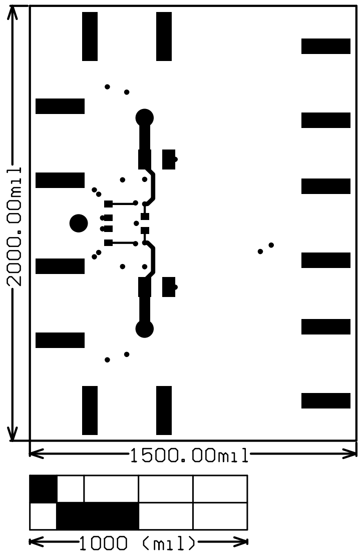
DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ______
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = M12[illegible]ons
PLOT NAME = LMH6552SDEVAL.GM11

BOARD #: SV600016
REV: A
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

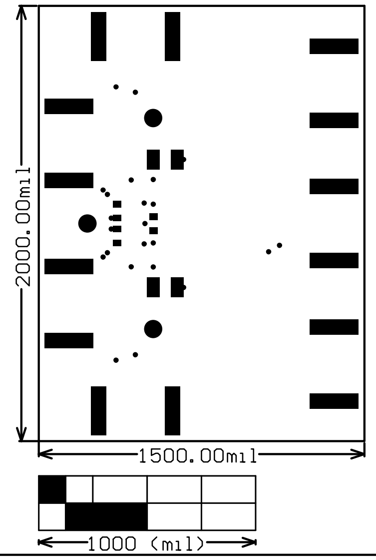
DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ________
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER ________
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ________
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ________
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ________
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ________
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = M11 Board Dimensions
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS

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TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

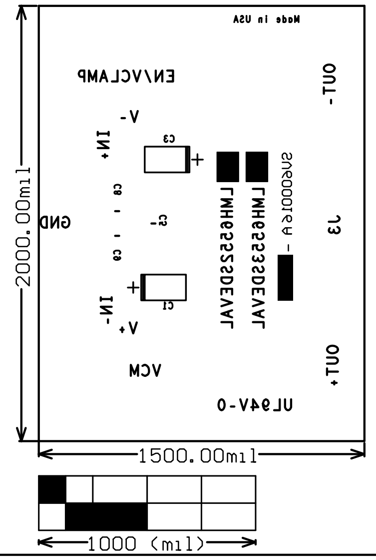
FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009



Layer Stack Up Detail for: LMH6552SDEVAL.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil				
				FR-4 High Tg	4.80	PrePreg
Layer2		1.4mil				
				FR-4 High Tg	4.80	Core
Layer3		1.4mil				
				FR-4 High Tg	4.80	PrePreg
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500MIL X 2000MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 30 MIL
MIN. VIA PAD SIZE: 25 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ________
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER________
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ________
COPPER THICKNESS (FINISHED):
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ________
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ________
SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER ________
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ________
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:
LMH6552SD Evaluation Board

DESIGNED FOR:
Public Release

FILE NAME:
LMH6552SDEVAL.PcbDoc

MODIFIED BY:
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:
10.0.0.27009

ALL ARTWORK VIEWED FROM TOP SIDE
BOARD #: SV600016
REV: A
LAYER NAME = M12 Board Dimensions
PLOT NAME = LMH6552SDEVAL.GM11
GENERATED : 8/14/2013 4:52:55 PM
TEXAS INSTRUMENTS